

IN THE SPECIFICATION:

On column 2, lines 1-14, please amend the paragraphs as follows:

FIG. 2 is a cross section view taken along the line [A-A] II-II in FIG. 1 wherein the openings extend through the bond pad.

FIG. 3 is a cross section view taken along the line [A-A] II-II in FIG. 1 wherein the openings extend only partially into the bond pad.

IN THE CLAIMS:

Claims 1, 16, 17, and 27-29 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity. Please enter these claims as amended. Also attached is a version with markings to show changes made to the claims.

1. (Twice Amended) A semiconductor device having an improved bond pad, the semiconductor device comprising:
- a bond pad electrically connected to an active circuit in the semiconductor device;
 - a substantially flat bonding surface on the bond pad; and
 - an opening extending into the bonding surface.
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2. A semiconductor device according to claim 1, further comprising a plurality of openings in the bonding surface of the bond pad.
3. A semiconductor device according to claim 2, wherein the openings are disposed about a center portion of the bonding surface of the bond pad so the center portion of the bonding surface is free of openings.